Ref #	Hits	Search Query	DBs	Default Operator	Plura ls	Time Stamp
S1	0	etch$3 and plasma and texur$5 with (screen$3 mesh shadow$3 adj mask)	US-PGPU B; USPAT	OR	ON	2005/09/13 09:27
S2	0	etch$3 and plasma and texur$5 same (screen$3 mesh shadow$3 adj mask)	US-PGPU B; USPAT	OR	ON	2005/05/27 19:44
S3	1	etch$3 and plasma and texur$5 and (screen$3 mesh shadow$3 adj mask)	US-PGPU B; USPAT	OR	ON	2005/05/27 19:46
S4	0	etch$3 and plasma and texur$5 and (screen$3 mesh shadow$3 adj mask)	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/05/27 19:52
S5	488	etch$3 and plasma and (texur$5 screen$3 mesh shadow$3 adj mask)	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/05/27 19:53
S6	22	etch$3 and plasma and (through near (screen$3 mesh shadow$3 adj mask))	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/05/27 20:02
S7	1122	etch$3 and plasma and (through near (screen$3 mesh shadow$3 adj mask))	US-PGPU B; USPAT	OR	ON	2005/05/27 20:03
S8	149	plasma and etch$3 same (through near (screen$3 mesh shadow$3 adj mask))	US-PGPU B; USPAT	OR	ON	2005/05/27 20:04
S9	59	plasma and etch$3 with (through near (screen$3 mesh shadow$3 adj mask))	US-PGPU B; USPAT	OR	ON	2005/05/27 20:04

S10	250	etch$3 and (screen$3 shaddow stencil) near mask$3	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 11:41
S11	4	S10 and (textur$3 rough$5 protrusion spike grass)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 10:11
S12	11	etch$3 and (template) near mask$3	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 10:44
S13	253	etch$3 and (wir$3 rod grid bar) near mask$3	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 10:51
S14	227	etch$3 and (wir$3) near mask$3	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 10:45
S15	88	etch$3 and (wir$3) adj mask$3	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 10:45
S16	71	etch$3 same (wir$3) adj mask$3	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 10:45
S17	55	etch$3 with (wir$3) adj mask$3	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 10:45

S18	26	etch$3 and (rod grid bar) near mask$3	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 11:37
S19	2	etch$3 and (noncontact non-contact) near mask$3	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 11:38
S20	4	etch$3 and (screen$3 shaddow stencil template wir$3 rod grid bar noncontact non-contact) near mask$3 and clean$3 near (screen$3 shaddow stencil template wir$3 rod grid bar noncontact non-contact)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 11:45
S21	12	etch$3 and (screen$3 shaddow stencil template wir$3 rod grid bar noncontact non-contact) near mask$3 and clean$3 with (screen$3 shaddow stencil template wir$3 rod grid bar noncontact non-contact)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 11:46
S22	57	etch$3 and (screen$3 shaddow stencil template wir$3 rod grid bar noncontact non-contact) with mask$3 and clean$3 with (screen$3 shaddow stencil template wir$3 rod grid bar noncontact non-contact)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 11:58
S23	17261	etch$3 and (screen$3 shaddow stencil template wir$3 rod grid bar noncontact non-contact) with mask$3	US-PGPUB; USPAT	OR	ON	2005/09/09 13:04

S24	3849	etch$3 and mask$3 near(screen$3 shaddow stencil template wir$3 rod grid bar noncontact non-contact)	US-PGPU B; USPAT	OR	ON	2005/09/09 11:59
S25	2108	etch$3 and mask$3 adj (screen$3 shaddow stencil template wir$3 rod grid bar noncontact non-contact)	US-PGPU B; USPAT	OR	ON	2005/09/09 11:59
S26	767	etch$3 same mask$3 adj (screen$3 shaddow stencil template wir$3 rod grid bar noncontact non-contact)	US-PGPU B; USPAT	OR	ON	2005/09/09 11:59
S27	486	etch$3 with mask$3 adj (screen$3 shaddow stencil template wir$3 rod grid bar noncontact non-contact)	US-PGPU B; USPAT	OR	ON	2005/09/09 11:59
S28	88	etch$3 near mask$3 adj (screen$3 shaddow stencil template wir$3 rod grid bar noncontact non-contact)	US-PGPU B; USPAT	OR	ON	2005/09/09 12:06
S29	11720	etch$3 and (screen$3 shaddow stencil template wire rod grid bar noncontact non-contact) with mask$3	US-PGPU B; USPAT	OR	ON	2005/09/12 17:40
S30	9673	etch$3 and (screen$3 shaddow stencil template rod grid bar noncontact non-contact) with mask$3	US-PGPU B; USPAT	OR	ON	2005/09/09 12:07
S31	3729	etch$3 same (screen$3 shaddow stencil template rod grid bar noncontact non-contact) with mask$3	US-PGPU B; USPAT	OR	ON	2005/09/09 12:07
S32	2201	etch$3 with (screen$3 shaddow stencil template rod grid bar noncontact non-contact) with mask$3	US-PGPU B; USPAT	OR	ON	2005/09/09 12:07

S33	521	etch$3 and (screen$3 shaddow stencil template wire rod grid bar noncontact non-contact) with mask$3 and clean$3 with (screen$3 shaddow stencil template wire rod grid bar noncontact non-contact)	US-PGPUB; USPAT	OR	ON	2005/09/09 12:08
S34	462	etch$3 same mask$3 with (screen$3 shaddow stencil template wire rod grid bar noncontact non-contact) and clean$3 with (mask$3 screen$3 shaddow stencil template wire rod grid bar noncontact non-contact)	US-PGPUB; USPAT	OR	ON	2005/09/09 12:09
S35	148	etch$3 same mask$3 near (screen$3 shaddow stencil template wire rod grid bar noncontact non-contact) and clean$3 with (mask$3 screen$3 shaddow stencil template wire rod grid bar noncontact non-contact)	US-PGPUB; USPAT	OR	ON	2005/09/09 12:09
S36	65	etch$3 same mask$3 near (screen$3 shaddow stencil template wire rod grid bar noncontact non-contact) and clean$3 near (mask$3 screen$3 shaddow stencil template wire rod grid bar noncontact non-contact)	US-PGPUB; USPAT	OR	ON	2005/09/09 12:14
S37	65	S36 not "which in turn requires the mask to be cleaned"	US-PGPUB; USPAT	OR	ON	2005/09/09 12:14
S38	65	S36 not "which in turn"	US-PGPUB; USPAT	OR	ON	2005/09/09 12:14
S39	65	S36 not "requires the mask to be cleaned"	US-PGPUB; USPAT	OR	ON	2005/09/09 12:15

S40	65	S36 not ((requires near mask near2 cleaned) and (which near turn))	US-PGPUB; USPAT	OR	ON	2005/09/09 12:16
S41	30	S36 not Leedy	US-PGPUB; USPAT	OR	ON	2005/09/09 12:16
S43	116	etch$3 and (screen$3 shaddow stencil template wire rod grid bar noncontact non-contact) with mask$3 and clean$3 with (turn$3 flip$4 backside revers$3)	US-PGPUB; USPAT	OR	ON	2005/09/09 12:39
S44	1	S43 not S42	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 12:27
S45	432	((216/12) or (216/45)). CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 12:40
S46	31	(216/45).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 12:41

S47	321	etch$3 and mask$3 with (screen$3 shaddow stencil template wire rod grid bar noncontact non-contact) and (turn$3 flip$4 backside revers$3) near (mask$3 screen$3 shaddow stencil template wire rod grid bar noncontact non-contact)	US-PGPUB; USPAT	OR	ON	2005/09/09 13:06
S48	163	etch$3 and mask$3 near (screen$3 shaddow stencil template wire rod grid bar noncontact non-contact) and (turn$3 flip$4 backside revers$3) near (mask$3 screen$3 shaddow stencil template wire rod grid bar noncontact non-contact)	US-PGPUB; USPAT	OR	ON	2005/09/12 17:56
S49	7649	S48 clean$3 near (mask$3 screen$3 shaddow stencil template wire rod grid bar noncontact non-contact)	US-PGPUB; USPAT	OR	ON	2005/09/09 13:07
S50	43	S48 and clean$3 near (mask$3 screen$3 shaddow stencil template wire rod grid bar noncontact non-contact)	US-PGPUB; USPAT	OR	ON	2005/09/09 13:07
S51	3216	S29 and (textur$3 rough$5 protrusion spike grass)	US-PGPUB; USPAT	OR	ON	2005/09/09 13:20
S52	1304	S29 and (textur$3 rough$5 protrusion spike grass) near (substrate workpiece wafer surface)	US-PGPUB; USPAT	OR	ON	2005/09/09 13:21
S53	231	S32 and (textur$3 rough$5 protrusion spike grass) near (substrate workpiece wafer surface)	US-PGPUB; USPAT	OR	ON	2005/09/09 13:22
S54	107	S34 and (textur$3 rough$5 protrusion spike grass) near (substrate workpiece wafer surface)	US-PGPUB; USPAT	OR	ON	2005/09/09 13:22

S55	38	S36 and (textur$3 rough$5 protrusion spike grass) near (substrate workpiece wafer surface)	US-PGPUB; USPAT	OR	ON	2005/09/09 13:23
S56	68	S47 and (textur$3 rough$5 protrusion spike grass) near (substrate workpiece wafer surface)	US-PGPUB; USPAT	OR	ON	2005/09/09 13:24
S57	47	S48 and (textur$3 rough$5 protrusion spike grass) near (substrate workpiece wafer surface)	US-PGPUB; USPAT	OR	ON	2005/09/09 13:24
S58	38	S50 and (textur$3 rough$5 protrusion spike grass) near (substrate workpiece wafer surface)	US-PGPUB; USPAT	OR	ON	2005/09/09 13:27
S59	97	S36 S50 S55 S56 S57 S58	US-PGPUB; USPAT	OR	ON	2005/09/09 13:27
S60	62	S59 not leedy	US-PGPUB; USPAT	OR	ON	2005/09/09 13:28
S61	1	(US-5868952-$).did.	USPAT	OR	OFF	2005/09/12 17:18
S62	0	S61 and RF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/12 17:19
S63	0	S61 and radio	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/12 17:19

S64	0	S61 and electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/12 17:19
S65	1	S61 and electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 17:37
S66	0	S61 and bias$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 17:37
S67	0	S61 and power	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 17:38
S68	1	S61 and frequency	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 17:38
S69	10	etch$3 and RF and (noncontact non-contact) with mask$3	US-PGPUB; USPAT	OR	ON	2005/09/12 18:08

S70	547	etch$3 and RF and (shadow) with mask$3	US-PGPUB; USPAT	OR	ON	2005/09/12 17:54
S71	199	etch$3 and mask$3 near (screen$3 shadow stencil template wire rod grid bar noncontact non-contact) and (turn$3 flip$4 backside revers$3) near (mask$3 screen$3 shadow stencil template wire rod grid bar noncontact non-contact)	US-PGPUB; USPAT	OR	ON	2005/09/13 09:28
S72	163	etch$3 and mask$3 near (screen$3 shaddow stencil template wire rod grid bar noncontact non-contact) and (turn$3 flip$4 backside revers$3) near (mask$3 screen$3 shaddow stencil template wire rod grid bar noncontact non-contact)	US-PGPUB; USPAT	OR	ON	2005/09/12 17:57
S73	36	S71 not S72	US-PGPUB; USPAT	OR	ON	2005/09/12 17:57
S74	106	etch$3 and RF and spaced adj apart with mask$3	US-PGPUB; USPAT	OR	ON	2005/09/12 18:08
S75	1	etch$3 and RF and spaced adj apart adj mask$3	US-PGPUB; USPAT	OR	ON	2005/09/12 18:08
S76	5074	etch$3 with mask$3 with (screen$3 shadow stencil template wire rod grid bar noncontact non-contact spaced apart)	US-PGPUB; USPAT	OR	ON	2005/09/13 10:26

S77	1961	S76 and plasma	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 09:30
S78	324	S77 and RF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 09:30
S79	10	S78 and (substrate wafer workpiece) near (mask$3 screen$3shadow stencil template wire rod grid bar noncontact non-contact) with (gap distance separation spaced apart)	US-PGPUB; USPAT	OR	ON	2005/09/13 09:40
S80	97	S76 and (substrate wafer workpiece) near (mask$3 screen$3shadow stencil template wire rod grid bar noncontact non-contact) with (gap distance separation spaced apart) not S79	US-PGPUB; USPAT	OR	ON	2005/09/13 10:06
S81	32	S77 and (substrate wafer workpiece) near (mask$3 screen$3shadow stencil template wire rod grid bar noncontact non-contact) with (gap distance separation spaced apart) not S79	US-PGPUB; USPAT	OR	ON	2005/09/13 09:41
S82	65	S80 not S81	US-PGPUB; USPAT	OR	ON	2005/09/13 10:07

S83	23	("4119688" | "4158589" | "4523971" | "4941942"). PN. OR ("4661203" | "5254215").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/13 09:54
S84	2690	etch$3 with mask$3 with (screen$3 shadow stencil template wire rod grid bar noncontact non-contact spaced apart)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 10:49
S85	16	S84 and (substrate wafer workpiece) near (mask$3 screen$3shadow stencil template wire rod grid bar noncontact non-contact) with (gap distance separation spaced apart) not S79	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 10:23
S86	438	clean$3 with mask$3 with (screen$3 shadow stencil template wire rod grid bar noncontact non-contact spaced apart)	US-PGPUB; USPAT	OR	ON	2005/09/13 10:47
S87	86	clean$3 near2 mask$3 near2 (screen$3 shadow stencil template wire rod grid bar noncontact non-contact spaced apart)	US-PGPUB; USPAT	OR	ON	2005/09/13 10:36
S88	122	S76 and S86	US-PGPUB; USPAT	OR	ON	2005/09/13 10:36
S89	91	S88 not (S79 S80 S83 S85 S87)	US-PGPUB; USPAT	OR	ON	2005/09/13 10:37
S90	333	clean$3 with mask$3 with (screen$3 shadow stencil template wire rod grid bar noncontact non-contact spaced apart)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 10:48
S91	116	clean$3 near2 mask$3 near2 (screen$3 shadow stencil template wire rod grid bar noncontact non-contact spaced apart)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 10:48

S92	30	S84 and S90	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 10:49
S93	5	S84 and S91	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 10:53